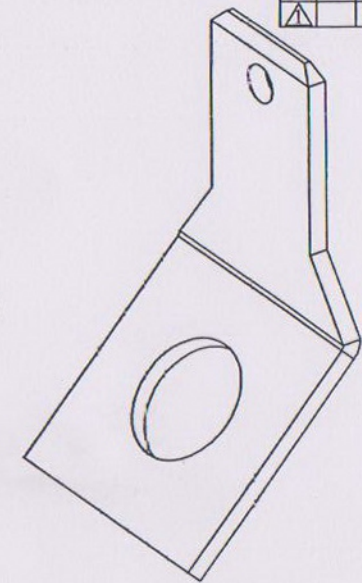
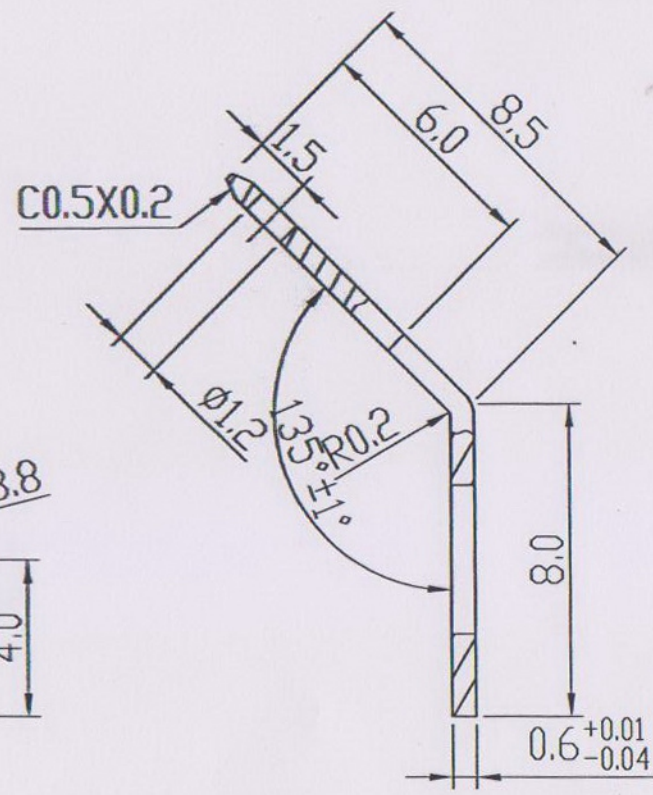
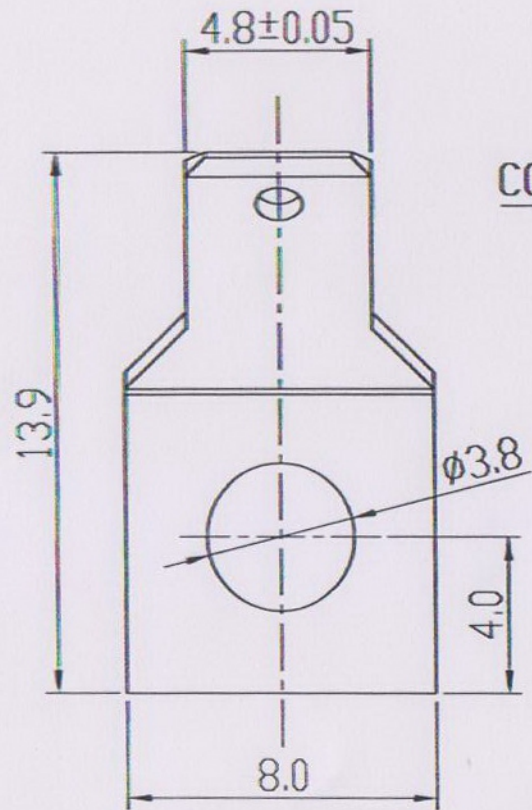


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	DATE
△		增加材料牌号,修改电镀标准	YHG	10/15/09



- Notes:
1. Material: H52 H/2, T=0.6mm;
 2. Plating: Cu plated at the bottom is more than 2um; Ni plated on the surface is more than 2um; Sn plated at the bottom is more than 4um;
 3. Undimensioned Tolerances:

Pitch range in mm		Nominal dimension range in mm						
to	over	to	over	to	over	to	to	
6	6	10	30	60	100	150	∩	
	to	to	to	to	to	to	□	
	0	20	30	60	100	150		
±0.10	±0.15	±0.25	±0.2	±0.3	±0.5	±0.7	±1.0	



1	K5	C0510	H62	SnCe	
ITEM	NAME OF PART	NO. OF PART	Q*TY	MATERIAL	NOTES
MM (INCH)		DATE 11/1/08	宁波高正电子有限公司 DEGSON ELECTRONICS CO., LTD		
TOLERANCES EXCEPT AS NOTED		CHKD WY	NAME K5-00A (H)		
.01 ± .02 ± .05 ±		DATE 10-30-09	DRAWING NO. K5-E01 /PART NO.		
ANGLES ± 1°		DATE 10-13-09	SIZE A4		
THIRD ANGLE PROJECTION		MATERIAL	REV T1		
FINISH		G.E.	SHEET 1 OF 1		
SCALE 1:1		DO NOT SCALE DRAWING	DATE 10/15/09		